

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2648240

SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
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<table border="1"> <tr> <td>Name:</td> <td>SEOUL VIOSYS CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>1B-36, 727-5, WONSI-DONG, DANWON-GU,</td> </tr> <tr> <td>Internal Address:</td> <td>GYEONGGI-DO,</td> </tr> <tr> <td>City:</td> <td>ANSAN-SI</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> <tr> <td>Postal Code:</td> <td>425-851</td> </tr> </table>		Name:	SEOUL VIOSYS CO., LTD.	Street Address:	1B-36, 727-5, WONSI-DONG, DANWON-GU,	Internal Address:	GYEONGGI-DO,	City:	ANSAN-SI	State/Country:	KOREA, REPUBLIC OF	Postal Code:	425-851				
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CORRESPONDENCE DATA																	
<p>Fax Number:</p> <p>Email: patent@park-law.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: H.C. PARK &amp; ASSOCIATES, PLC</p> <p>Address Line 1: 1894 PRESTON WHITE DRIVE</p> <p>Address Line 4: RESTON, VIRGINIA 20191</p>																	
ATTORNEY DOCKET NUMBER:	P5705US00																

NAME OF SUBMITTER:	MATTHEW T. GILL
Signature:	/M. T. Gill/
Date:	12/13/2013
	This document serves as an Oath/Declaration (37 CFR 1.63).
<p>Total Attachments: 8 source=P5705US00_AssignmentDeclaration#page1.tif source=P5705US00_AssignmentDeclaration#page2.tif source=P5705US00_AssignmentDeclaration#page3.tif source=P5705US00_AssignmentDeclaration#page4.tif source=P5705US00_AssignmentDeclaration#page5.tif source=P5705US00_AssignmentDeclaration#page6.tif source=P5705US00_AssignmentDeclaration#page7.tif source=P5705US00_AssignmentDeclaration#page8.tif</p>	



**ASSIGNMENT SERVING AS DECLARATION PER 37 C.F.R. § 1.63(e)**

As a below named inventor and Assignor, I declare that:

This assignment and declaration are directed to:

☒ The attached application entitled **EPITAXIAL LAYER WAFER HAVING VOID FOR SEPARATING GROWTH SUBSTRATE THEREFROM AND SEMICONDUCTOR DEVICE FABRICATED USING THE SAME** having attorney docket number **P5705US00** ("Application"), which claims priority from:  
Korean Patent Application No. 10-2012-0146329, filed December 14, 2012  
Korean Patent Application No. 10-2012-0150389, filed December 21, 2012

☐ As amended on \_\_\_\_\_ (if applicable);

The above-identified Application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the Application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in the Application,

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

**SEOUL VIOSYS CO., LTD.**  
1B-36, 727-5, Wonsi-dong, Danwon-gu  
Gyeonggi-do  
Ansan-si 425-851  
Republic of Korea

**SEOUL VIOSYS CO., LTD.** herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and



HC Park & Associates, PLC

COUNSELORS at LAW

Docket No. P5705US00

related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Inventor and Assignor has hereunto set hand and seal.

First Inventor's and Assignor's Name: Jong Min JANG

Address: 1B-36, 727-5, Wonsi-dong, Danwon-gu  
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Ansan-si 425-851  
Republic of Korea

First Inventor's and Assignor's Signature: Jong Min Jang

Date: 2013. 12. 13

Second Inventor's and Assignor's Name: Kyu Ho LEE

Address: 1B-36, 727-5, Wonsi-dong, Danwon-gu  
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Republic of Korea

Second Inventor's and Assignor's Signature: Kyu Ho Lee

Date: 2013. 12. 13



Third Inventor's and Assignor's Name: Chang Suk HAN

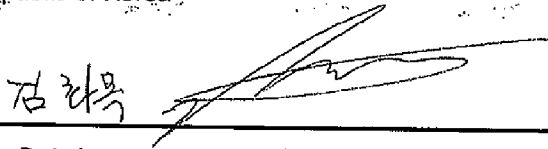
Address: 1B-36, 727-5, Wonsi-dong, Danwon-gu  
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Ansan-si 425-851  
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Third Inventor's and Assignor's Signature: 

Date: December, 12, 2013

Fourth Inventor's and Assignor's Name: Hwa Mok KIM

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Fourth Inventor's and Assignor's Signature: 

Date: DEC 12, 2013

Fifth Inventor's and Assignor's Name: Daewoong Suh

Address: 1B-36, 727-5, Wonsi-dong, Danwon-gu  
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Republic of Korea

Fifth Inventor's and Assignor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_



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Sixth Inventor's and Assignor's Name: Chi Hyun IN

Address: 1B-36, 727-5, Wonsi-dong, Danwon-gu  
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Ansan-si 425-851  
Republic of Korea

Sixth Inventor's and Assignor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

2013. 12. 13

Seventh Inventor's and Assignor's Name: Jong Hyeon CHAE

Address: 1B-36, 727-5, Wonsi-dong, Danwon-gu  
Gyeonggi-do  
Ansan-si 425-851  
Republic of Korea

Seventh Inventor's and Assignor's  
Signature: \_\_\_\_\_

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First Inventor's and Assignor's Name: Jong Min JANG

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First Inventor's and Assignor's Signature: Jong Min Jang

Date: 2013. 12. 13

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Second Inventor's and Assignor's Signature: Kyu Ho Lee

Date: 2013. 12. 13





Third Inventor's and Assignor's Name: Chang Suk HAN

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Third Inventor's and Assignor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Fourth Inventor's and Assignor's Name: Hwa Mok KIM

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Fourth Inventor's and Assignor's  
Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Fifth Inventor's and Assignor's Name Daewoong Suh

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Republic of Korea

Fifth Inventor's and Assignor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

*Daewoong Suh*  
Dec 12, 2013



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Sixth Inventor's and Assignor's Name: Chi Hyun IN

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Ansan-si 425-851  
Republic of Korea

Sixth Inventor's and Assignor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

2013. 12. 13

Seventh Inventor's and Assignor's Name: Jong Hyeon CHAE

Address: 1B-36, 727-5, Wonsi-dong, Danwon-gu  
Gyeonggi-do  
Ansan-si 425-851  
Republic of Korea

Seventh Inventor's and Assignor's  
Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Dec. 12. 2013